TO.: MINDA NO.: M201124



APPROVAL SHEET

MULTILAYER CERAMIC CAPACITOR
Commercial Grade
(High Voltage Type (100V~3000V))
(IEC-60384 Qualified)

Approved by customer : (signing or stamping here)	

SAMWHA CAPACITOR CO., LTD.							
Writtern by	Approved by						
21-85	gros 1	7/-					

2020. 11. 24.



Address : 124, BUK-RI, NAMSA-MYUN YOUNGIN-SI, KYUNGKI-DO, KOREA

Contact : TEL 82-31-332-6441 , FAX 82-31-332-7661

Home page: www.samwha.com

< SPEC SUMMARY >									
SAMWHA Part no.		CS3	225X7R225K101NRK						
Type		High voltage							
Item	Specification	Test methods and Conditions(Capacitance,IR)							
Capacitance	2.2	μF							
Capacitance Tolerance	± 10	%	Testing Frequency: 1 ±0.2kHz Testing Voltage: 1 ±0.2Vrms						
Dissipation Factor	Max. 5	%	Testing voitage . 1 ±0.2 viiiis						
Insulation Resistance	More than 45.4	MΩ	Applied the rated voltage for 2 minutes of charging.						
	3.20 ±0.40	L (mm)	*Capacitance Tolerance Code page 1/9						
Chip Size	2.50 ±0.25	W (mm)	*Chip size page 2/9						
	2.00 ±0.25	T (mm)	*Characteristics & Test Method page 3/9~6/9						

Enactment :	STANDARD	NO	SW - M - 04B
March 27,1996	MULTILAYER CERAMIC CAPACITOR	Dogo	1 / 0
,	Commercial Grade	Page	1 / 9

1. General Article

Application Range

These specifications refer to the "Multilayer Ceramic Capacitors "mainly used to the computer equipment, communication equipment.

*Caution: Industrial equipment / For the high reliability equipment / LED equipment / Etc.

Please contact sales representatives or product engineers before using the products.

(For details, please refer Page 9)

2. General Code

(1) Type Designation

<u>CS</u>	<u>3225</u>	<u>X7R</u>	<u>225</u>	<u>K</u>	<u>101</u>	<u>N</u>	<u>R</u>	K
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- 1) Multilayer Ceramic Capacitor (Commercial Grade)
- 2) Size Code:

This is expressed in tens of a millimeter.

The first two digits are the length, The last two digits are width.

3) Temperature Coefficient Code

Classification	Code	Temperature Range	Capacitance Tolerance
Class I	C0G	-55 to +125℃	±30 ppm/℃
	X5R	-55 to +85℃	±15%
Class II	X7R	-55 to +125℃	±15%
	Y5V	-30 to +85℃	+22% ~ -82%

4) Capacitance Code(Pico farads):

The nominal Capacitance Value in pF is expressed by three digit numbers.

The first two digits represents significant figures and the last digit denotes the number of zero ex) 104 = 100000 pF

R denotes decimal

8R2 = 8.2 pF

5) Capacitance Tolerance Code

Code	Tolerance
В	± 0.1 pF
С	± 0.25 pF
D	± 0.5 pF
F	± 1.0 %
G	± 2.0 %
J	± 5 %
K	± 10 %

Code	Tolerance
М	± 20 %
Р	+ 100, -0%
Z	+ 80, -20%
Н	+ 0.25/-0 pF
I	+ 0/-0.25 pF
U	+ 5/-0 %
V	+ 0/-5 %

6) Voltage Code

code	6R3	100	160	250	350	500	101	201	251	501	631	102	202	302
\/al	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC
Vol.	6.3V	10V	16V	25V	35V	50V	100V	200V	250V	500V	630V	1KV	2KV	3KV

7) Termination Code

ex) N: Ni-Sn (Nickel-Tin Plate)

A: Ag/Ni-Sn (Ag Epoxy/Nickel-Tin Plate) -> Soft Termination Type

8) Packing Code

ex) R: 7" Reel Type L: 13" Reel Type B: Bulk Type

9) Thickness option

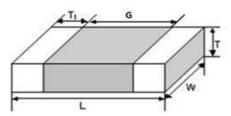
Thickne	Thickness(mm)		Thickness(mm)		Thickness(mm)		Thickne	ss(mm)	Code
t	Tol(±)	Code	t	Tol(±)	0000				
0.30	0.03	Blank	1.30	0.20	Е				
0.50	0.05	Blank	1.35	0.20	Н				
0.60	0.10	А	1.60	0.20	1				
0.80	0.10	В	1.80	0.20	J				
0.85	0.15	В	2.00	0.25	K				
1.00	0.15	Е	2.50	0.25	L				
1.10	0.15	Е	2.80	0.30	М				
1.15	0.15	Е	3.20	0.30	N				
1.25	0.15	Е	5.00	0.40	0				

3. Temperature Characteristics

See Page 3/9 (No.7)

4. Constructions and Dimensions

(I) Dimensions



(Unit: mm)

	Dimension									
Code	Ler	ıgth	Wi	dth	T1(min)	C(min)				
	L	Tol(±)	W	Tol(±)	T1(min)	G(min)				
0603	0.60	0.03	0.30	0.03	0.05	0.15				
1005	1.00	0.05	0.50	0.05	0.05	0.30				
1608	1.60	0.15	0.80	0.10	0.10	0.50				
2012	2.00	0.20	1.25	0.15	0.10	0.65				
3216	3.20	0.30	1.60	0.20	0.15	1.00				
3225	3.20	0.40	2.50	0.25	0.15	1.05				
4520	4.50	0.40	2.00	0.25	0.20	1.50				
4532	4.50	0.40	3.20	0.30	0.20	1.50				
5750	5.70	0.50	5.00	0.40	0.30	1.85				

(2) Construction of Termination



Specifications and Test Methods (High voltage type)

		Spe	Test Methods and Conditions					
No.	ltem	Class I	Class II		res	t Method	is and Condition	S
1	Operating Temperature Range	C0G :-55 to+125℃	X7R : −55 to +125°C					
2	Dimensions	Within the specified dimen	sion	Using	calipers			
3	Voltage proof	No defects or abnormali	ties	betwee is less		nations, pro- bitage 30V 150 22kV 120 33.15kV 150	H when voltage in tab vided the charge/disc Test voltage 0% of the rated voltage 0% of the rated voltage 0% of the rated voltage	Time e e 1to5 sec.
4	Insulation Resistance	More than 10,000 MΩ	-DC100V~1KV :C≥0.01μF:More than 100MΩ·μF :C<0.01μF:More than 10,000MΩ -DC2~3KV:More than6,000 MΩ					stance should
5	Capacitance	within the specified tolerance		Cap	Testing	g frequency	Testing Voltage	Measure temperature
6	Dissipation Factor	COG Char.: 30pFmin : Q≥1,000(DF≤0.1%) 30pFmax : Q≥400+20C (DF≤1/ (400+20C))	30pFmin : Q≥1,000(DF≤0.1%) 30pFmax : Q≥400+20C		measuren rm the init rding to No	ial measu ote1 for C fter test	AC 1±0.2Vrms rement	25℃
7	Temperature characteristic of capacitance	Temp. Coefficient C0G char.: 0±30ppm/°C (Temp. Range: -55to+125°C)	Cap. Change within ±15% (Temp. Range: -55 to +125°C)	Take it out and set it for 24±2 hours (Class I) of 24±2 hours (Class II) then measure COG: The temperature coefficient is determined using capacitance measured in step 3 as a reference. When cycling the temperature sequentially from step 1 through 5 the capacitance should be within the specific tolerance for the temperature coefficient. Step Temperature(°C) 1 25±2 2 -55±3 3 25±2 4 125±3 (for COG) 5 25±2 X7R: The range of capacitance change compared with 25°C value should be within the specified range. Pretreatment Perform a heat treatment at 150 -10, +0°C for 60±5min, and then let sit for 24±2hrs.(Class I), 24±2hrs.(Class II) at room Temperature			d using the step 1 specified	

			Specific	cation					
No.	lí	tem	Class I	Class II	Test Methods and Conditions				
8	8 Adhesive Strength of Termination		No removal of the terminations or other defect should occur		Solder the capacitor to the testing jig(glass epoxy board) shown in Fig. 1 using a eutectic solder. Then apply 10N force in the direction of the arrow. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. 10N(5N:Size 1.6×0.8mm only), 10±1s Speed: 1.0mm/s Glass Epoxy Board				
		Appearance	No defects or abnormalities	3					
		Capacitance	Within the specified tolerance		The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency				
9	Vibration	Dissipation Factor(or Q)	COG Char.: 30pFmin : Q≥1,000(DF≤0.1%) 30pFmax : Q≥400+20C (DF≤1/ (400+20C))	5% max	being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 min. This motion should be applied for a period of 2hrs. in each 3mutually perpendicular directions(total of 6hrs.)				
10	Substrate bending test		(mm) a 1.6×0.8 1.0 3 2.0×1.25 1.2 4 3.2×1.6 2.2 5 3.2×2.5 2.2 5 4.5×2.0 3.5 7	occur. t:1.6 mension(mm) b	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 2 using a eutectic solder. Then apply a force in the direction shown in Fig. 3. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. 20 50 Pressurizing speed: 1.0mm/s Pressurize (in mm) * Test condition Bending limit: 1mm Pressurizing speed: 1mm/sec Holding time: 5±1sec				
11	Solderability		95% of the terminations is and continuously.	to be soldered evenly	Immerse the capacitor in a solution of ethanol and rosin(25% rosin in weight proportion). Immerse in eutectic solder solution for 2±0.5 sec. at 245±5°C. Immersing speed: 25±2.5mm/s				

	o. Item		Spe							
No.			Class I	Class II	•	Test Meth	est Methods and Conditions			
	Appea		No defects which may	affect performance	4			150°C * for 1 m		
		Capacitance change	within ±2.5%or ±0.25pF (whichever is larger) COG Char. :	within ±10%	Immerse the capacitor in eutec 260±5℃ for 10±1 sec.		tic solder soluti	on at		
12	Resistance to Soldering Heat	Dissipation Factor (or Q)	30pFmin : Q≥1,000(DF≤0.1%) 30pFmax : Q≥400+20C (DF≤1/ (400+20C))	5% max	-Immersing speed: 25±2.5 ·Initial measurement Perform the initial meas according to Note1 for 0 ·Measurement after test Let sit at room Temperature 1			ment		
		I.R.	More than 10,000MΩ	-DC100V~1KV :C≥0.01 µF:More than 100M\\(\Omega\) µF :C<0.01 µF:More than 10,000M\(\Omega\) -DC2~3KV:More than1,000 M\(\Omega\)	24±2hrs.(Class I), 24±2hrs.(Clas		7 Time 1 min			
		Appearance	No defects which may	affect performance	Darfarm the	o E ovologia		to the 4 best to	rootmonto	
		Capacitance Change	Within ±2.5%or ±0.25pF (whichever is larger)	within ±15%	listed in the	-	_	to the 4 heat to	4	
		Dissipation	COG Char. : 30pFmin		Temp Min	operating emp. ±3	Room Temp	Max. operating temp. ±2	Room Temp	
13	Rapid change of temperature	reature Factor (or Q) 30pFmax : Q≥400+20C	: Q≥400+20C	5% max	Time (min) 30±3 2 to3 30±3 2 to3 •Initial measurement					
		I.R	(DF≦1/ (400+20C)) More than 10,000MΩ	-DC100V~1KV :C≥0.01 µF:More than 100MΩ· µF :C<0.01 µF:More than 10,000MΩ -DC2~3KV:More than 3,000MΩ	Perform the initial measurement according to Note1 for Class II •Measurement after test Perform the final measurement according to Note2					
		Appearance	No defects which may affect performance Let the capacitor sit at 40±2℃ and relative							
		Capacitance Change	within ±5% or ±0.5pF (Whichever is larger)	Within ±15%	90 to 95%	and relative hu	midity of			
14	Damp heat, steady state	Dissipation Factor (or Q)	COG Char. : $C \ge 30 pF$: $Q \ge 275 + \frac{5}{2}/C$	7.5% max	·Initial mea Perform to Note	ing				
		I.R	More than 1,000MΩ	-DC100V~1KV :C≥0.01μF:More than 10MΩ·μF :C<0.01μF:More than 1,000MΩ -DC2~3KV:More than 1,000MΩ	Measurement after test Perform the final measurement according to Note2					
		Appearance	No defects which may	affect performance	Apply the		ollowing t	able		
		Capacitance Change	within ±3% or ±0.3pF (Whichever is larger)	DC100V,630V:Within ±15% DC1KV:Within ±20% DC2~3KV:Within ±20%	for 1,000+48/-0hrs. at maximum operating temperature ±3°C. The charge/discharge current is less than 50mA.			Α.		
		Dissipation COG Char. : $C \ge 30 pF : Q \ge 350$ (or Q) $C < 30 pF : Q \ge 275 + \frac{5}{2} / C$	7.5% max	Operating temperature range	Rated vo	Itage	Test voltage			
			7.0% max	COG	Rated volta ≥DC1KV	Rat	ed voltage			
15	Endurance	- /			Rated volta <dc1kv< td=""><td>120</td><td>% of the rated v</td><td>oltage/</td></dc1kv<>	120	% of the rated v	oltage/		
	Endurance		-DC100V~1KV	X7R	DC100V~2 DC500V~6 DC1KV~D0	30V 120	% of the rated v 1% of the rated v 1% of the rated v	oltage/		
			:C≥0.01 µF:More than 10M\Q:µF :C<0.01 µF:More than 1,000M\Q -DC2~3KV:More than 2,000M\Q	Initial measurement Perform the initial measurement according to Note1 for Class II Independent after test Perform the final measurement according to Note2						

			S	pecification			
No.	 	tem	Class I	Class II	Test Methods and Conditions		
		Appearance		No defects which may affect performance	Apply the rated voltage at 40±2°C and relative		
	Humidity Load	Capacitance Change		Within ±15%	humidity of 90 to 95 for 500+24/-0 hrs. Initial measurement		
16	(Application : DC250V	Dissipation (or Q)		7.5% max	Perform the initial measurement according to Note1 for Class II		
	item)	I.R.		C≥0.01 µF:More than 10MQ·µF C<0.01 µF:More than 1,000MQ	Measurement after test Perform the final measurement according to Note2		

*Note1. Initial Measurement for Class II

Perform a heat treatment at 150+0,-10℃ for one hour and then let sit for 24±2 hours at room temperature, then measure

- *Note2. Measurement after test
 - 1.Class I

Let sit for 24±2 hours at room temperature, then measurement

2.Class II

Perform a heat treatment at 150+0,-10℃ for one hour and then let sit for 24±2 hours at room temperature, then measure.

"Following the International standards, the title of each test item is subject to change."

5. Packing

- (1) Bulk packing
 - 1 1000 pcs per Polybag
 - 2 5 Polybags per Inner box
 - 3 10 Inner boxes per Out box
- (2) Reel Packing
 - ① 8~10 Reels per Inner box
 - 2 6 Inner boxes per Out box
- (3) Reel Dimensions



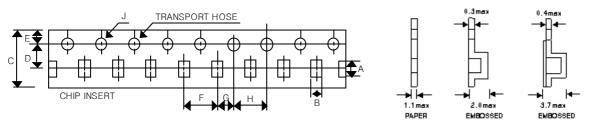


						(L	Jnit: mm)
MARK	SIZE	Α	В	С	D	E	W
7 " REEL	0603~3225	Φ178±2	Ф50Min	Ф13±0.5	Φ21±0.8	2±0.5	10±1.5
/ REEL	4520~4532	Ф180+0,-3	Ф60-0,+1	Φ13±0.2	Ф57-0+1	3±0.2	13±0.5
13 " REEL	1005~3225	Ф330±2	Φ70Min	Ф13±0.5	Φ21±0.8	2±0.5	10±1.5

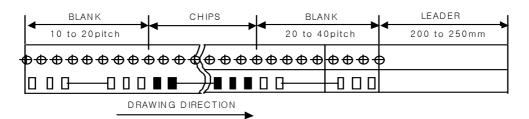
(4) Number of Package

TYPF	EIA CODE	7"	13"
ITPE	EIA CODE	Qt/REEL	Qt/REEL
CS0603	CC0201	15,000	
CS1005	CC0402	10,000	50,000
CS1608	CC0603	4,000	15,000
CS2012	CC0805	3,000 ~ 4,000	8,000 ~ 15,000
CS3216	CC1206	2,000 ~ 4,000	6,000 ~ 10,000
CS3225	CC1210	1,000 ~ 3,000	4,000 ~ 10,000
CS4520	CC1808	1,500 ~ 3,000	_
CS4532	CC1812	500 ~ 1,000	1,500 ~ 5,000

(5) Tape Dimensions



TYPE	EIA CODE	А	В	С	D	Е	F	G	Н	J
CS0603	CC0201	0.67±0.05	0.37±0.05	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
CS1005	CC0402	1.15±0.1	0.65±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
CS1608	CC0603	1.9±0.2	1.10±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS2012	CC0805	2.4±0.2	1.65±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS3216	CC1206	3.6±0.2	2.00±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS3225	CC1210	3.6±0.2	2.80±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS4520	CC1808	4.8±0.2	2.3±0.2	12.0±0.3	5.5±0.1	1.75±0.1	4.0±0.1 8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS4532	CC1812	4.9±0.2	3.6±0.2	12.0±0.3	5.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1



6.Caution

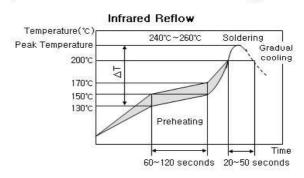
► Reflow Soldering

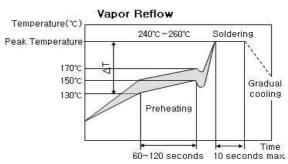
- 1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.
- 2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference $(\triangle T)$ within the range recommended in Table 1.

Table 1

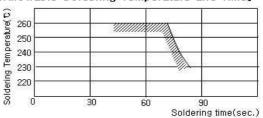
Size code	Temperature Difference
0603, 1005, 1608, 2012, 3216	△T≤190°C
3225size and over	△T≤130°C

[Standard Conditions for Reflow Soldering]





[Allowable Soldering Temperature and Time]



In case of repeated soldering, the accumulated soldering time must be within the range shown above.

► Storage Condition

*When Solderability is considered, Capacitor are recommended to be used in 12 months

(1) Temperature: 25° C ± 10° C

(2) Relative Humidity: Below 70% RH

▶ The Regulation of Environmental Pollution Materials.

*Never use materials mentioned below in MLCC products regulated this document.

Pb, Cd, Hg, Cr⁺⁶, PBB(Polybromide biphenyl), PBDE(Polybrominated diphenyl ethers), asbestos.

* Note

(1) 'Aging'/'De-aging' Behavior of high dielectric MLCCs

(Typically represented by X7R, Y5V temperature characteristic of which main composition is BaTiO3)

'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric Ceramic Capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

$$C_t = C_{24} (1 - k \log 10 t)$$

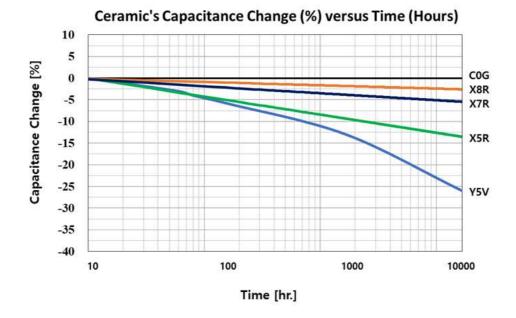
where:

Ct = Capacitance Value, t hours after the start of 'aging'

C₂₄ = Capacitance Value. 24 hours after its manufacture

k = aging constant (capacitance decrease per decade-hour)

t = time, in hours, from the start of 'aging'



The capacitance value can be restored (a.k.a. 'de-aged') by exposing the component to elevated temperatures approaching its Curie Temperature (approximately 120°C). This 'deaging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing., or by 'baking 'at 150°C for about 1 hour.

- (2) Please contact our sales representatives or product engineers before using the products in this catalog for the applications listed below, which require especially high reliability for the prevention of defects which might directly damage a third party's life, body or property, or when one of our products is intended for use in applications other than those specified in this catalog.
 - ①Aircraft equipment
- ②Aerospace equipment
- ③Undersea equipment

- ©Transportation equipment (vehicles, trains, ships, etc.)
- Traffic signal equipment Spisaster prevention / crime prevention equipment

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

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Other Similar products are found below:

M39014/02-1218V M39014/02-1225V M39014/22-0631 D55342E07B523DR-T/R NIN-FB391JTRF NIN-FC2R7JTRF

NMC0402NPO220J50TRPF NMC0402X5R105K6.3TRPF NMC0402X5R224K6.3TRPF NMC0402X7R103J25TRPF

NMC0402X7R153K16TRPF NMC0603NPO101F50TRPF NMC0603NPO1R8C50TRPF NMC0603NPO201J50TRPF

NMC0603X5R475M6.3TRPF NMC0805NPO270J50TRPF NMC0805NPO681F50TRPF NMC0805NPO820J50TRPF

NMC0805X7R224K16TRPLPF NMC0805X7R224K25TRPF NMC1206X7R102K50TRPF NMC1206X7R475K10TRPLPF NMC-Q0402NPO8R2D200TRPF C1206C101J1GAC C1608C0G2A221J C1608X7R1E334K C2012C0G2A472J 2220J2K00562KXT

1812J2K00332KXT CDR04BX104AKSR CDR31BX103AKWR CDR33BX104AKUR CDR33BX683AKUS CGA2B2C0G1H010C CGA2B2C0G1H040C CGA2B2C0G1H050C CGA2B2C0G1H060D CGA2B2C0G1H070D CGA2B2C0G1H120J CGA2B2C0G1H151J CGA2B2C0G1H1R5C CGA2B2C0G1H2R2C CGA2B2C0G1H390J CGA2B2C0G1H391J CGA2B2C0G1H3R3C CGA2B2C0G1H680J CGA2B2C0G1H6R8D CGA2B2C0G1H820J CGA2B2X8R1H152K CGA2B2X8R1H221K